

	Hits	Search Text	DBs	Time Stamp
1	5	("6766576" "6571467" "6112408").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:08
2	209	(form forming formed) near3 bump adj pad and flip adj chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:50
3	53	(form forming formed) near3 bump adj pad and flip adj chip and electroless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:11
4	6	(form forming formed) near3 bump adj pad and flip adj chip and electroless and pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:11
5	3	(form forming formed) near3 bump adj pad and flip adj chip and electroless and pulse and direct adj current	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:11
6	7	bump and flip adj chip and electroless and pulse and direct adj current	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:12
7	28	bump and electroless and pulse and direct adj current	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:12
8	15	bump and electroless and pulse adj (plating plated plate) and direct adj current	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:17
9	15	bump and electroless and pulse adj (plating plated plate) and direct adj current and electrolytic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:45

	Hits	Search Text	DBs	Time Stamp
10	12	("5519177" "4642163" "5258094" "5021296" "5200271" "5699613").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:28
11	13	("5419926" "3322881" "4482596" "4265943" "4528259").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:29
12	4	("3929593").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:29
13	12	("4777078" "5055321" "5741575" "5780143" "6217987" "6251502").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:32
14	0	pct/jp99/05003.pct.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:35
15	12	("4777078" "5055321" "5741575" "5780143" "6217987" "6251502").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:37
16	6	("4642163" "5021296" "5258094").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:38
17	0	jp-0448099-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:39
18	2	jp-04048099-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:40

	Hits	Search Text	DBs	Time Stamp
19	2	jp-02238691-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:40
20	2	jp-09135077-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:41
21	2	jp-09199855-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:41
22	4	"9905003".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:43
23	1	wo-9905003-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:43
24	3	bump and electroless and pulse adj (plating plated plate) and direct adj current with electrolytic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:45
25	69	(form forming formed) near3 bump adj pad and flip adj chip and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:51
26	28	(form forming formed) near3 bump adj pad and flip adj chip and "438"/\$.ccls. and electroless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:51
27	27	(form forming formed) near3 bump adj pad and flip adj chip and "438"/\$.ccls. and electroless and (plate plating plated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:51

	Hits	Search Text	DBs	Time Stamp
28	3	(form forming formed) near3 bump adj pad and flip adj chip and "438"/\$.ccls. and electroless and (plate plating plated) and electrolytic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:52
29	1	(form forming formed) near3 bump adj pad and flip adj chip and "438"/\$.ccls. and electroless and (plate plating plated) and pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:52
30	50	bump and flip adj chip and "438"/\$.ccls. and electroless and (plate plating plated) and pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:53
31	35	bump and flip adj chip and "438"/\$.ccls. and electroless and (plate plating plated) and pulse and electrolytic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:54
32	17	bump and flip adj chip and "438"/\$.ccls. and electroless and (plate plating plated) and pulse and electrolytic and photoresist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/19 21:54